

WHAT IS CLAIMED IS:

- 1 1. A circuit sheet, comprising:
2 a substrate; and
3 wells disposed on the substrate and operable to hold respective conductive
4 polymers that form circuit devices.
- 1 2. The sheet of claim 1, further comprising:
2 a first set of ridges formed in a first direction on the substrate;
3 a second set of ridges formed in a second direction on the substrate, the
4 second direction being substantially perpendicular to the first direction; and
5 wherein the wells are defined by respective intersections of the first and
6 second sets of ridges.
- 1 3. The sheet of claim 1 wherein the substrate is flexible.
- 1 4. A circuit sheet, comprising:
2 a substrate; and
3 a treatment disposed on regions of the substrate and operable to limit the
4 sizes of conductive-polymer dots printed onto the regions.
- 1 5. An electronic device, comprising:
2 a substrate;
3 conductive polymer dots disposed on the substrate in predetermined locations;
4 and
5 a connection layer that interconnects the dots to form a circuit.
- 1 6. The circuit electronic device of claim 5, further comprising a display
2 disposed on the connection layer and operable to be driven by the circuit.
- 1 7. The circuit of claim 5 wherein at least one of the conductive polymer
2 dots comprises polymer poly-paraphenylene vinylene poly-paraphenylene (PPP).
- 1 8. The circuit of claim 5 further comprising wells formed on the substrate
2 in the predetermined locations and holding the dots.
- 1 9. The circuit of claim 5 wherein the predetermined locations of the
2 substrate are treated to limit the size of the dots.

- 1 10. A circuit sheet, comprising:
2 a substrate; and
3 circuit components disposed on the substrate and formed from a conductive
4 polymer.
- 1 11. The circuit sheet of claim 10 wherein the circuit components are
2 isolated from one and other.
- 1 12. A circuit, comprising:
2 a substrate;
3 circuit components disposed on the substrate and formed from a conductive
4 polymer; and
5 conductive traces disposed on the substrate and interconnecting the circuit
6 components in a predetermined topology.
- 1 13. The circuit of claim 12, further comprising a display disposed on the
2 substrate and operable to be driven by the interconnected circuit components.
- 1 14. A method, comprising:
2 forming a first set of ridges on a substrate; and
3 forming a second set of ridges on the substrate such that the first and second
4 sets of ridges define wells operable to receive and hold respective conductive
5 polymers.
- 1 15. The method of claim 14 wherein forming the first and second sets of
2 ridges comprise printing the first and second sets of ridges onto the substrate.
- 1 16. The method of claim 14 wherein forming the first and second sets of
2 ridges comprise stamping the first and second sets of ridges onto the substrate.
- 1 17. The method of claim 14 wherein forming the second set of ridges
2 comprises forming the ridges of the second set substantially perpendicular to the
3 ridges of the first set.
- 1 18. A method, comprising:
2 forming circuit components from dots of a conductive polymer on a substrate;
3 and
4 interconnecting the circuit components to form a circuit.

1 19. The method of claim 18 wherein forming circuit components comprises
2 filling wells on the substrate with the conductive polymer.

1 20. The method of claim 18 wherein forming circuit components comprises
2 treating the substrate to limit the sizes of the dots.

1 21. A method, comprising:
2 acquiring a substrate on which are disposed conductive polymer circuit
3 components; and
4 interconnecting the conductive-polymer circuit components to form a circuit.